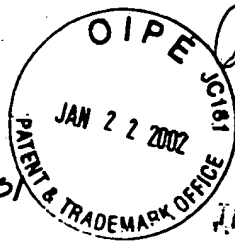


CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with The United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on December 17, 2001

Gwyn J. Cantrell

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ART UNIT 2813

TECHNOLOGY CENTER 2800
Docket No. 740756-2064

In re Patent application of:)

Shunpei YAMAZAKI et al.)

Serial No.: 09/437,135)

Group Art Unit: 2813

Filed: November 10, 1999)

Examiner: E. Kielin

For: SEMICONDUCTOR DEVICE AND)

METHOD FOR FORMING THE SAME)

AMENDMENT AFTER FINAL REJECTION

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Responsive to the Office Action dated **September 17, 2001**, the following amendments and remarks are submitted in connection with the above-identified application.

IN THE CLAIMS:

Please amended claims 1, 6, 11, 30, and 34 as follows. Attached hereto is a marked up copy of the claims in their amended form.

1. (Thrice Amended) A method for manufacturing a semiconductor device comprising the steps of:
- forming a semiconductor film comprising amorphous silicon over a substrate;
 - crystallizing said semiconductor film by irradiating a laser light;
 - patterning the crystallized semiconductor film to form first and second semiconductor islands;
 - forming an insulating film on each of said first and second semiconductor islands by a vapor phase deposition;